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Details

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Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	EBI/EMI, SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	60
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s12gc96cfue

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Chapter 1 MC9S12C and MC9S12GC Device Overview (MC9S12C128)



The figure shows a useful map, which is not the map out of reset. After reset the map is: 0x0000–0x03FF: Register Space

0x0000-0x0FFF: 4K RAM (only 3K visible 0x0400-0x0FFF)

Flash erase sector size is 1024 bytes

Figure 1-2. MC9S12C128 and MC9S12GC128 User Configurable Memory Map



Chapter 1 MC9S12C and MC9S12GC Device Overview (MC9S12C128)

1.3.4 Detailed Signal Descriptions

1.3.4.1 EXTAL, XTAL — Oscillator Pins

EXTAL and XTAL are the crystal driver and external clock pins. On reset all the device clocks are derived from the EXTAL input frequency. XTAL is the crystal output.

1.3.4.2 RESET — External Reset Pin

 $\overline{\text{RESET}}$ is an active low bidirectional control signal that acts as an input to initialize the MCU to a known start-up state. It also acts as an open-drain output to indicate that an internal failure has been detected in either the clock monitor or COP watchdog circuit. External circuitry connected to the $\overline{\text{RESET}}$ pin should not include a large capacitance that would interfere with the ability of this signal to rise to a valid logic one within 32 ECLK cycles after the low drive is released. Upon detection of any reset, an internal circuit drives the $\overline{\text{RESET}}$ pin low and a clocked reset sequence controls when the MCU can begin normal processing.

1.3.4.3 TEST / V_{PP} — Test Pin

This pin is reserved for test and must be tied to V_{SS} in all applications.

1.3.4.4 XFC — PLL Loop Filter Pin

Dedicated pin used to create the PLL loop filter. See CRG BUG for more detailed information.PLL loop filter. Please ask your Motorola representative for the interactive application note to compute PLL loop filter elements. Any current leakage on this pin must be avoided.



Figure 1-10. PLL Loop Filter Connections

1.3.4.5 BKGD / TAGHI / MODC — Background Debug, Tag High, and Mode Pin

The BKGD / TAGHI / MODC pin is used as a pseudo-open-drain pin for the background debug communication. In MCU expanded modes of operation when instruction tagging is on, an input low on this pin during the falling edge of E-clock tags the high half of the instruction word being read into the instruction queue. It is also used as a MCU operating mode select pin at the rising edge during reset, when the state of this pin is latched to the MODC bit.



Chapter 2 Port Integration Module (PIM9C32) Block Description

2.1 Introduction

The Port Integration Module establishes the interface between the peripheral modules and the I/O pins for all ports.

This chapter covers:

- Port A, B, and E related to the core logic and the multiplexed bus interface
- Port T connected to the TIM module (PWM module can be routed to port T as well)
- Port S connected to the SCI module
- Port M associated to the MSCAN and SPI module
- Port P connected to the PWM module, external interrupt sources available
- Port J pins can be used as external interrupt sources and standard I/O's

The following I/O pin configurations can be selected:

- Available on all I/O pins:
 - Input/output selection
 - Drive strength reduction
 - Enable and select of pull resistors
- Available on all Port P and Port J pins:
 - Interrupt enable and status flags

The implementation of the Port Integration Module is device dependent.

2.1.1 Features

A standard port has the following minimum features:

- Input/output selection
- 5-V output drive with two selectable drive strength
- 5-V digital and analog input
- Input with selectable pull-up or pull-down device

Optional features:

- Open drain for wired-OR connections
- Interrupt inputs with glitch filtering



Chapter 3 Module Mapping Control (MMCV4) Block Description

Stretch Bit EXSTR1	Stretch Bit EXSTR0	Number of E Clocks Stretched
0	0	0
0	1	1
1	0	2
1	1	3

Table 3-6. External Stretch Bit Definition

3.3.2.5 Reserved Test Register 0 (MTST0)

Module Base + 0x0014

Starting address location affected by INITRG register setting.



Figure 3-7. Reserved Test Register 0 (MTST0)

Read: Anytime

Write: No effect — this register location is used for internal test purposes.

3.3.2.6 Reserved Test Register 1 (MTST1)

Module Base + 0x0017

Starting address location affected by INITRG register setting.



Figure 3-8. Reserved Test Register 1 (MTST1)

Read: Anytime

Write: No effect — this register location is used for internal test purposes.



Chapter 6 Background Debug Module (BDMV4) Block Description

The commands are described as follows:

- ACK_ENABLE enables the hardware handshake protocol. The target will issue the ACK pulse when a CPU command is executed by the CPU. The ACK_ENABLE command itself also has the ACK pulse as a response.
- ACK_DISABLE disables the ACK pulse protocol. In this case, the host needs to use the worst case delay time at the appropriate places in the protocol.

The default state of the BDM after reset is hardware handshake protocol disabled.

All the read commands will ACK (if enabled) when the data bus cycle has completed and the data is then ready for reading out by the BKGD serial pin. All the write commands will ACK (if enabled) after the data has been received by the BDM through the BKGD serial pin and when the data bus cycle is complete. See Section 6.4.3, "BDM Hardware Commands," and Section 6.4.4, "Standard BDM Firmware Commands," for more information on the BDM commands.

The ACK_ENABLE sends an ACK pulse when the command has been completed. This feature could be used by the host to evaluate if the target supports the hardware handshake protocol. If an ACK pulse is issued in response to this command, the host knows that the target supports the hardware handshake protocol. If the target does not support the hardware handshake protocol the ACK pulse is not issued. In this case, the ACK_ENABLE command is ignored by the target because it is not recognized as a valid command.

The BACKGROUND command will issue an ACK pulse when the CPU changes from normal to background mode. The ACK pulse related to this command could be aborted using the SYNC command.

The GO command will issue an ACK pulse when the CPU exits from background mode. The ACK pulse related to this command could be aborted using the SYNC command.

The GO_UNTIL command is equivalent to a GO command with exception that the ACK pulse, in this case, is issued when the CPU enters into background mode. This command is an alternative to the GO command and should be used when the host wants to trace if a breakpoint match occurs and causes the CPU to enter active background mode. Note that the ACK is issued whenever the CPU enters BDM, which could be caused by a breakpoint match or by a BGND instruction being executed. The ACK pulse related to this command could be aborted using the SYNC command.

The TRACE1 command has the related ACK pulse issued when the CPU enters background active mode after one instruction of the application program is executed. The ACK pulse related to this command could be aborted using the SYNC command.

The TAGGO command will not issue an ACK pulse because this would interfere with the tagging function shared on the same pin.



Chapter 9 Clocks and Reset Generator (CRGV4) Block Description

The PLL filter can be manually or automatically configured into one of two possible operating modes:

• Acquisition mode

In acquisition mode, the filter can make large frequency corrections to the VCO. This mode is used at PLL start-up or when the PLL has suffered a severe noise hit and the VCO frequency is far off the desired frequency. When in acquisition mode, the TRACK status bit is cleared in the CRGFLG register.

• Tracking mode

In tracking mode, the filter makes only small corrections to the frequency of the VCO. PLL jitter is much lower in tracking mode, but the response to noise is also slower. The PLL enters tracking mode when the VCO frequency is nearly correct and the TRACK bit is set in the CRGFLG register.

The PLL can change the bandwidth or operational mode of the loop filter manually or automatically.

In automatic bandwidth control mode (AUTO = 1), the lock detector automatically switches between acquisition and tracking modes. Automatic bandwidth control mode also is used to determine when the PLL clock (PLLCLK) is safe to use as the source for the system and core clocks. If PLL LOCK interrupt requests are enabled, the software can wait for an interrupt request and then check the LOCK bit. If CPU interrupts are disabled, software can poll the LOCK bit continuously (during PLL start-up, usually) or at periodic intervals. In either case, only when the LOCK bit is set, is the PLLCLK clock safe to use as the source for the system and core clocks and the LOCK bit is clear, the PLL has suffered a severe noise hit and the software must take appropriate action, depending on the application.

The following conditions apply when the PLL is in automatic bandwidth control mode (AUTO = 1):

- The TRACK bit is a read-only indicator of the mode of the filter.
- The TRACK bit is set when the VCO frequency is within a certain tolerance, Δ_{trk} , and is clear when the VCO frequency is out of a certain tolerance, Δ_{unt} .
- The LOCK bit is a read-only indicator of the locked state of the PLL.
- The LOCK bit is set when the VCO frequency is within a certain tolerance, Δ_{Lock} , and is cleared when the VCO frequency is out of a certain tolerance, Δ_{unl} .
- CPU interrupts can occur if enabled (LOCKIE = 1) when the lock condition changes, toggling the LOCK bit.

The PLL can also operate in manual mode (AUTO = 0). Manual mode is used by systems that do not require an indicator of the lock condition for proper operation. Such systems typically operate well below the maximum system frequency (f_{sys}) and require fast start-up. The following conditions apply when in manual mode:

- ACQ is a writable control bit that controls the mode of the filter. Before turning on the PLL in manual mode, the ACQ bit should be asserted to configure the filter in acquisition mode.
- After turning on the PLL by setting the PLLON bit software must wait a given time (t_{acq}) before entering tracking mode (ACQ = 0).
- After entering tracking mode software must wait a given time (t_{al}) before selecting the PLLCLK as the source for system and core clocks (PLLSEL = 1).



Chapter 10 Freescale's Scalable Controller Area Network (S12MSCANV2)

10.4.7.1 Description of Interrupt Operation

The MSCAN supports four interrupt vectors (see Table 10-36), any of which can be individually masked (for details see sections from Section 10.3.2.6, "MSCAN Receiver Interrupt Enable Register (CANRIER)," to Section 10.3.2.8, "MSCAN Transmitter Interrupt Enable Register (CANTIER)").

NOTE

The dedicated interrupt vector addresses are defined in the Resets and Interrupts chapter.

Interrupt Source	CCR Mask	Local Enable
Wake-Up Interrupt (WUPIF)	l bit	CANRIER (WUPIE)
Error Interrupts Interrupt (CSCIF, OVRIF)	l bit	CANRIER (CSCIE, OVRIE)
Receive Interrupt (RXF)	l bit	CANRIER (RXFIE)
Transmit Interrupts (TXE[2:0])	l bit	CANTIER (TXEIE[2:0])

Table 10-36. Interrupt Vectors

10.4.7.2 Transmit Interrupt

At least one of the three transmit buffers is empty (not scheduled) and can be loaded to schedule a message for transmission. The TXEx flag of the empty message buffer is set.

10.4.7.3 Receive Interrupt

A message is successfully received and shifted into the foreground buffer (RxFG) of the receiver FIFO. This interrupt is generated immediately after receiving the EOF symbol. The RXF flag is set. If there are multiple messages in the receiver FIFO, the RXF flag is set as soon as the next message is shifted to the foreground buffer.

10.4.7.4 Wake-Up Interrupt

A wake-up interrupt is generated if activity on the CAN bus occurs during MSCN internal sleep mode. WUPE (see Section 10.3.2.1, "MSCAN Control Register 0 (CANCTL0)") must be enabled.

10.4.7.5 Error Interrupt

An error interrupt is generated if an overrun of the receiver FIFO, error, warning, or bus-off condition occurrs. Section 10.3.2.5, "MSCAN Receiver Flag Register (CANRFLG) indicates one of the following conditions:

- **Overrun** An overrun condition of the receiver FIFO as described in Section 10.4.2.3, "Receive Structures," occurred.
- **CAN Status Change** The actual value of the transmit and receive error counters control the CAN bus state of the MSCAN. As soon as the error counters skip into a critical range (Tx/Rx-warning, Tx/Rx-error, bus-off) the MSCAN flags an error condition. The status change, which caused the error condition, is indicated by the TSTAT and RSTAT flags (see Section 10.3.2.5,



Chapter 10 Freescale's Scalable Controller Area Network (S12MSCANV2)



12.3.2.11 Reserved Registers (PWMSCNTx)

The registers PWMSCNTA and PWMSCNTB are reserved for factory testing of the PWM module and are not available in normal modes.

Module Base + 0x000A

Module Base + 0x000B



Figure 12-13. Reserved Register (PWMSCNTA)



Figure 12-14. Reserved Register (PWMSCNTB)

Read: always read 0x0000 in normal modes

Write: unimplemented in normal modes

NOTE

Writing to these registers when in special modes can alter the PWM functionality.



Chapter 13 Serial Communications Interface (S12SCIV2) Block Description

13.3 Memory Map and Registers

This section provides a detailed description of all memory and registers.

13.3.1 Module Memory Map

The memory map for the SCI module is given below in Figure 13-2. The Address listed for each register is the address offset. The total address for each register is the sum of the base address for the SCI module and the address offset for each register.

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
02000	SCIBDH	R	0	0	0	SBB12	SBB11	SBB10	SBBO	SBB8
0,0000	GOIDDIT	w				ODITIZ	ODITI	OBITIO	ODI13	ODITO
0x0001	SCIBDL	R W	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
0x0002	SCICR1	R	LOOPS	SCISWAI	RSRC	М	WAKE	ILT	PE	PT
0x0003	SCICR2	R W	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x0004	SCISB1	R	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0,0004	0010111	w								
0x0005	SCISB2	R	0	0	0	0	0	BBK13		RAF
0,0000	0010112	w						Drii(10	INDIR	
0x0006	x0006 SCIDRH	R	R8	тя	0	0	0	0	0	0
0,0000		w		10						
0×0007	SCIDBI	R	R7	R6	R5	R4	R3	R2	R1	R0
0,0001	COIDITE	w	T7	T6	T5	T4	Т3	T2	T1	Т0
		Г]= Unimplen	nented or R	leserved				

Figure 13-2. SCI Register Summary

13.3.2 Register Descriptions

This section consists of register descriptions in address order. Each description includes a standard register diagram with an associated figure number. Writes to a reserved register location do not have any effect and reads of these locations return a zero. Details of register bit and field function follow the register diagrams, in bit order.



14.1.3 Block Diagram

Figure 14-1 gives an overview on the SPI architecture. The main parts of the SPI are status, control, and data registers, shifter logic, baud rate generator, master/slave control logic, and port control logic.



Figure 14-1. SPI Block Diagram

14.2 External Signal Description

This section lists the name and description of all ports including inputs and outputs that do, or may, connect off chip. The SPIV3 module has a total of four external pins.

14.2.1 MOSI — Master Out/Slave In Pin

This pin is used to transmit data out of the SPI module when it is configured as a master and receive data when it is configured as slave.



Chapter 16 Dual Output Voltage Regulator (VREG3V3V2) Block Description

16.2.3 V_{DD}, V_{SS} — Regulator Output1 (Core Logic)

Signals V_{DD}/V_{SS} are the primary outputs of VREG3V3V2 that provide the power supply for the core logic. These signals are connected to device pins to allow external decoupling capacitors (100 nF...220 nF, X7R ceramic).

In Shutdown Mode an external supply at V_{DD}/V_{SS} can replace the voltage regulator.

16.2.4 V_{DDPLL}, V_{SSPLL} — Regulator Output2 (PLL)

Signals V_{DDPLL}/V_{SSPLL} are the secondary outputs of VREG3V3V2 that provide the power supply for the PLL and oscillator. These signals are connected to device pins to allow external decoupling capacitors (100 nF...220 nF, X7R ceramic).

In Shutdown Mode an external supply at V_{DDPLL}/V_{SSPLL} can replace the voltage regulator.

16.2.5 V_{REGEN} — Optional Regulator Enable

This optional signal is used to shutdown VREG3V3V2. In that case V_{DD}/V_{SS} and V_{DDPLL}/V_{SSPLL} must be provided externally. Shutdown Mode is entered with V_{REGEN} being low. If V_{REGEN} is high, the VREG3V3V2 is either in Full Performance Mode or in Reduced Power Mode.

For the connectivity of V_{REGEN} see device overview chapter.

NOTE

Switching from FPM or RPM to shutdown of VREG3V3V2 and vice versa is not supported while the MCU is powered.

16.3 Memory Map and Register Definition

This subsection provides a detailed description of all registers accessible in VREG3V3V2.

16.3.1 Module Memory Map

Figure 16-2 provides an overview of all used registers.

Table 16-2. VREG3	V3V2 Memory	Мар
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Address Offset	Use	Access
0x0000	VREG3V3V2 Control Register (VREGCTRL)	R/W



Chapter 17 16 Kbyte Flash Module (S12FTS16KV1)

Figure 17-9 illustrates all possible protection scenarios. Although the protection scheme is loaded from the Flash array after reset, it is allowed to change in normal modes. This protection scheme can be used by applications requiring re-programming in single chip mode while providing as much protection as possible if no re-programming is required.



Figure 17-9. Flash Protection Scenarios

17.3.2.5.1 Flash Protection Restrictions

The general guideline is that protection can only be added, not removed. All valid transitions between Flash protection scenarios are specified in Table 17-11. Any attempt to write an invalid scenario to the FPROT register will be ignored and the FPROT register will remain unchanged. The contents of the FPROT register reflect the active protection scenario.

From Protection Scenario	To Protection Scenario ⁽¹⁾					
	0	1	2	3		
0	Х	Х				
1		Х				
2		Х	Х			

Table 17-11. Flash Pro	tection Scenario	Transitions
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18.3.2.4 Flash Configuration Register (FCNFG)

The FCNFG register enables the Flash interrupts and gates the security backdoor key writes.



Figure 18-7. Flash Configuration Register (FCNFG)

CBEIE, CCIE, and KEYACC are readable and writable while remaining bits read 0 and are not writable. KEYACC is only writable if the KEYEN bit in the FSEC register is set to the enabled state (see Section 18.3.2.2).

Field	Description
7 CBEIE	 Command Buffer Empty Interrupt Enable — The CBEIE bit enables the interrupts in case of an empty command buffer in the Flash module. 0 Command Buffer Empty interrupts disabled 1 An interrupt will be requested whenever the CBEIF flag is set (see Section 18.3.2.6)
6 CCIE	 Command Complete Interrupt Enable — The CCIE bit enables the interrupts in case of all commands being completed in the Flash module. 0 Command Complete interrupts disabled 1 An interrupt will be requested whenever the CCIF flag is set (see Section 18.3.2.6)
5 KEYACC	 Enable Security Key Writing. 0 Flash writes are interpreted as the start of a command write sequence 1 Writes to the Flash array are interpreted as a backdoor key while reads of the Flash array return invalid data

Table 18-7. FCNFG Field Descriptions

18.3.2.5 Flash Protection Register (FPROT)

The FPROT register defines which Flash sectors are protected against program or erase.

Module Base + 0x0004



The FPROT register is readable in normal and special modes. FPOPEN can only be written from a 1 to a 0. FPLS[1:0] can be written anytime until FPLDIS is cleared. FPHS[1:0] can be written anytime until



18.4.1.3.4 Mass Erase Command

The mass erase operation will erase all addresses in a Flash array using an embedded algorithm.

An example flow to execute the mass erase operation is shown in Figure 18-25. The mass erase command write sequence is as follows:

- 1. Write to a Flash array address to start the command write sequence for the mass erase command. The address and data written will be ignored.
- 2. Write the mass erase command, 0x41, to the FCMD register.
- 3. Clear the CBEIF flag in the FSTAT register by writing a 1 to CBEIF to launch the mass erase command.

If a Flash array to be erased contains any protected area, the PVIOL flag in the FSTAT register will set and the mass erase command will not launch. Once the mass erase command has successfully launched, the CCIF flag in the FSTAT register will set after the mass erase operation has completed unless a new command write sequence has been buffered.



Chapter 19 64 Kbyte Flash Module (S12FTS64KV4)

19.1.3 Modes of Operation

See Section 19.4.2, "Operating Modes" for a description of the Flash module operating modes. For program and erase operations, refer to Section 19.4.1, "Flash Command Operations".

19.1.4 Block Diagram

Figure 19-1Figure 19-2 shows a block diagram of the FTS128K1FTS64K module.







MCU Address Range	PPAGE	Protectable Low Range	Protectable High Range	Array Relative Address ⁽¹⁾
0x0000-0x3FFF ⁽²⁾	Unpaged (0x3D)	N.A.	N.A.	0x14000-0x17FFF
0x4000-0x7FFF	Unpaged	0x4000–0x43FF	N.A.	0x18000-0x1BFFF
	(0x3E)	0x4000–0x47FF		
		0x4000–0x4FFF		
		0x4000-0x5FFF		
0x8000-0xBFFF	0x3A	N.A.	N.A.	0x08000-0x0BFFF
	0x3B	N.A.	N.A.	0x0C000-0x0FFFF
	0x3C	N.A.	N.A.	0x10000-0x13FFF
	0x3D	N.A.	N.A.	0x14000-0x17FFF
	0x3E	0x8000-0x83FF	N.A.	0x18000-0x1BFFF
		0x8000–0x87FF		
		0x8000-0x8FFF		
		0x8000-0x9FFF		
	0x3F	N.A.	0xB800-0xBFFF	0x1C000-0x1FFFF
			0xB000–0xBFFF	
			0xA000–0xBFFF	
			0x8000-0xBFFF	
0xC000–0xFFFF	Unpaged	N.A.	0xF800-0xFFFF	0x1C000-0x1FFFF
	(0x3F)		0xF000-0xFFFF	
			0xE000-0xFFFF	
			0xC000-0xFFFF	

Table 20-3	. Flash	Array	Memory	/ Мар	Summary
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1. Inside Flash block.

2. If allowed by MCU.



Appendix A Electrical Characteristics



NOTE

Figure A-1 shows only definitions, for specification values refer to Table A-12.



Appendix C Package Information

C.1 General

This section provides the physical dimensions of the packages 48LQFP, 52LQFP, 80QFP.